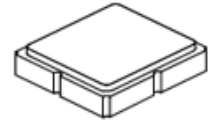


- **Low-loss RF SAW Filter**
- **Miniature 3 x 3 mm SMD Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

SF2740E

**1675 MHz
SAW Filter**



SM3030-6

Absolute Maximum Ratings

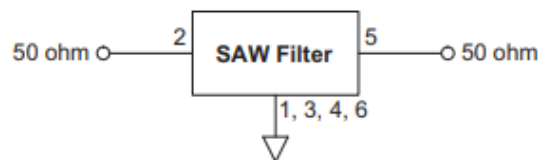
Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-grounded Terminal	3	V
Operable Temperature Range	-40 to +85	°C
Storage Temperature Range	-40 to +85	°C
Maximum Soldering Profile, 2 cycles/10 seconds minimum	260	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			1675		MHz
Insertion Loss, 1625 - 1725 MHz	IL			3.7	4.2	dB
Amplitude Ripple, 1625 - 1725 MHz				1.0	1.8	dB
VSWR, 1625 - 1725 MHz				1.7	2.4	
Attenuation, Referenced to 0 dB:						dB
50 to 1250 MHz			25	30		
1250 to 1540 MHz			20	31		
1820 to 3000 MHz			25	32		
Load / Source Impedance	Z_s Z_L			50		Ω
Temperature Coefficient of Frequency				-80		ppm/K
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	B n, YWWS					
Standard Reel Quantity	Reel Size 7 inch					500 Pieces/Reel
	Reel Size 13 inch					3000 Pieces/Reel

Electrical Connections

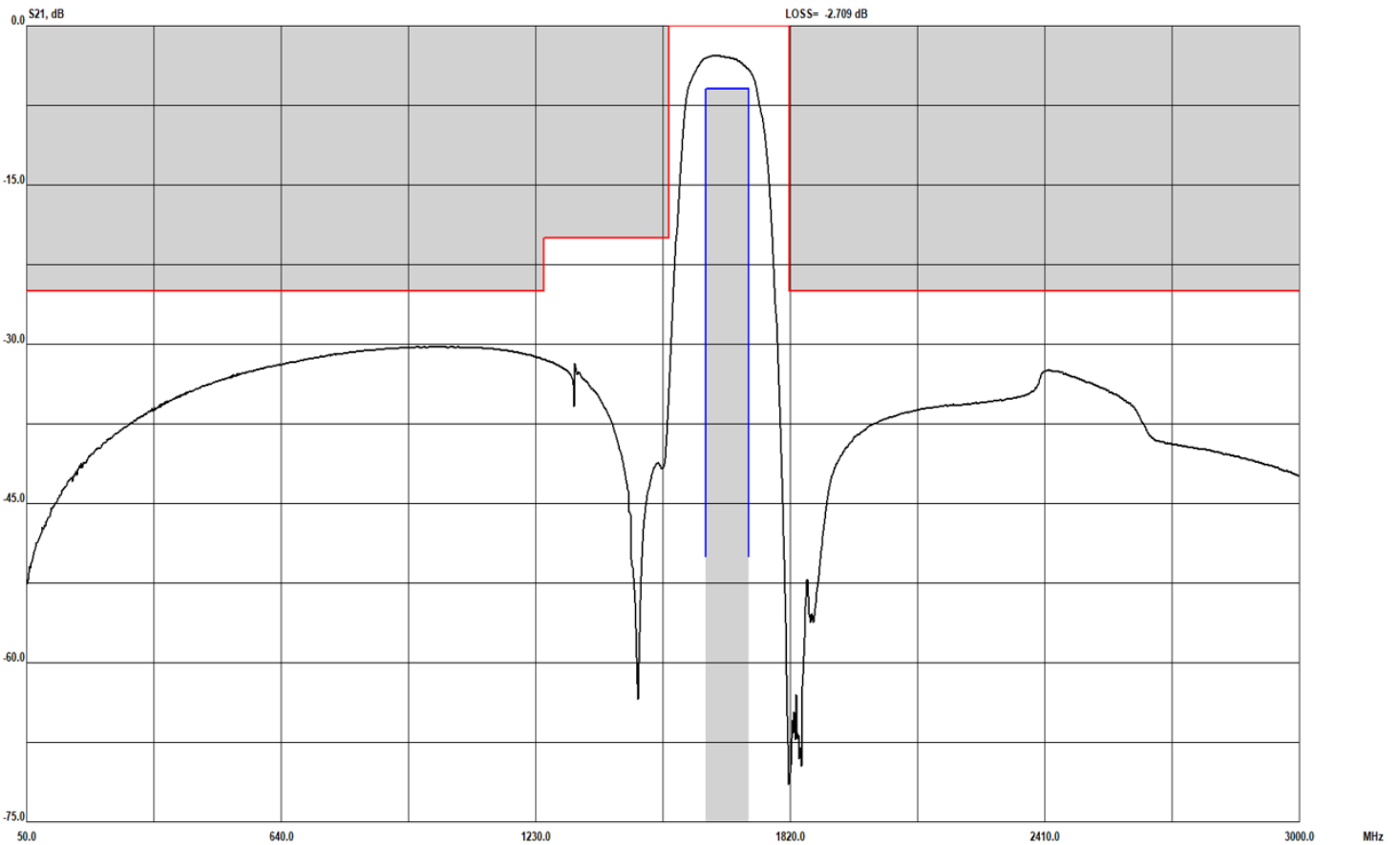
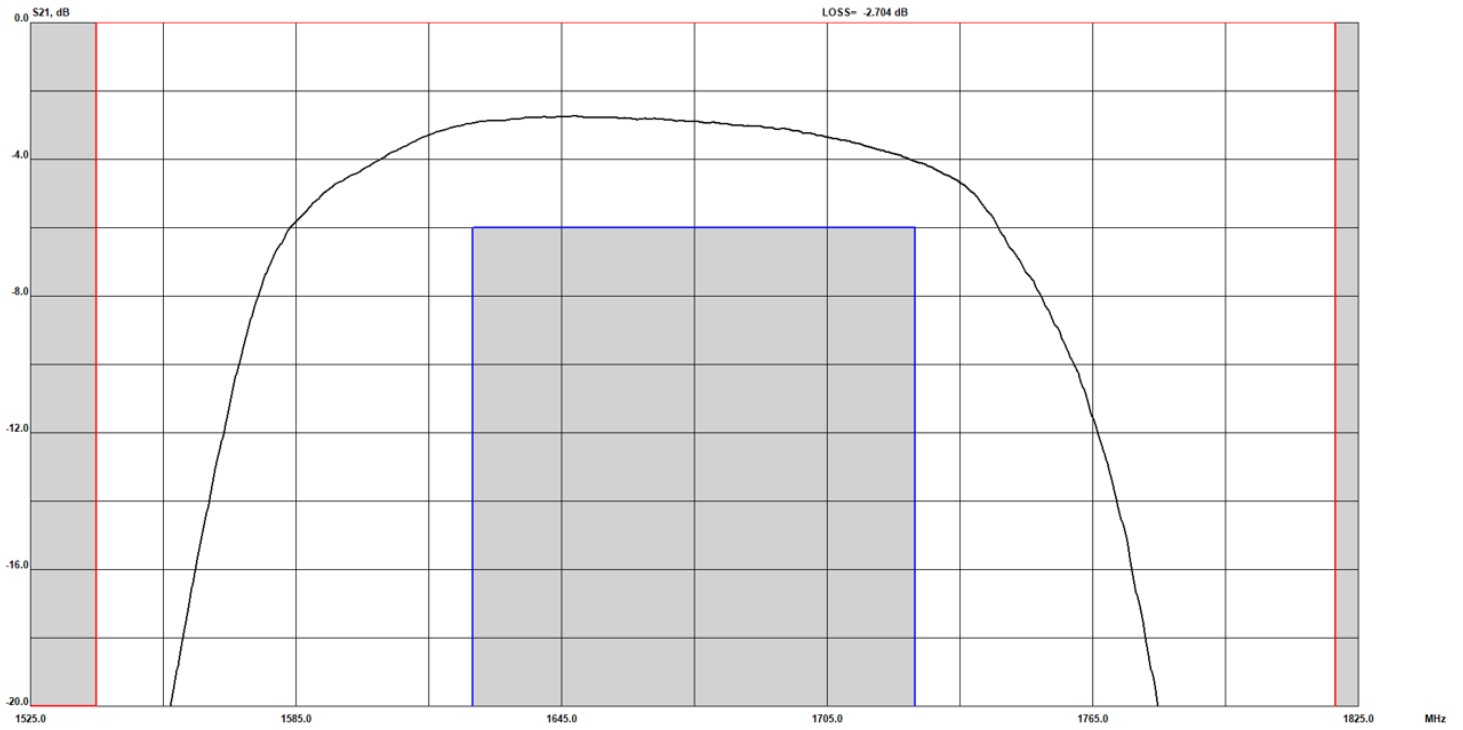
Connection	Terminals
Input	2
Output	5
Case Ground	All others



 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**
NOTES:

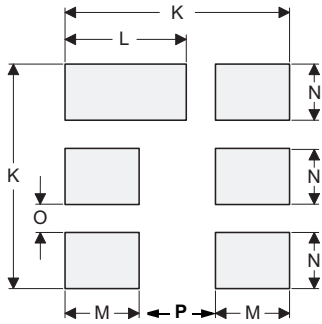
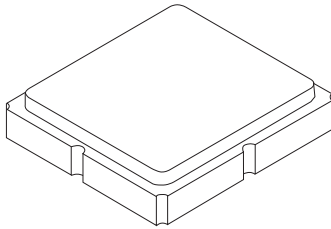
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Frequency Characteristics



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

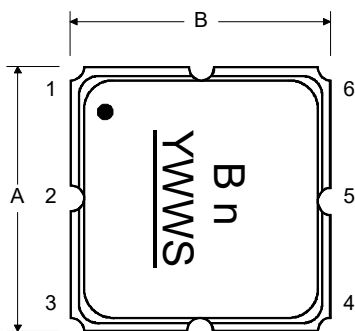
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	-	-	1.40	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K	-	3.20	-	-	0.126	-
L	-	1.70	-	-	0.067	-
M	-	1.05	-	-	0.041	-
N	-	0.81	-	-	0.032	-
O	-	0.38	-	-	0.015	-
P	-	1.09	-	-	0.039	-

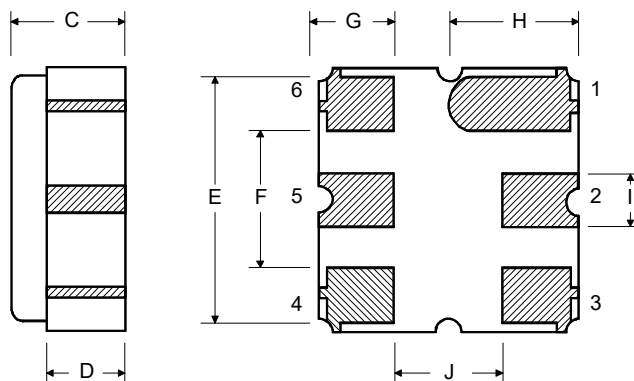
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW

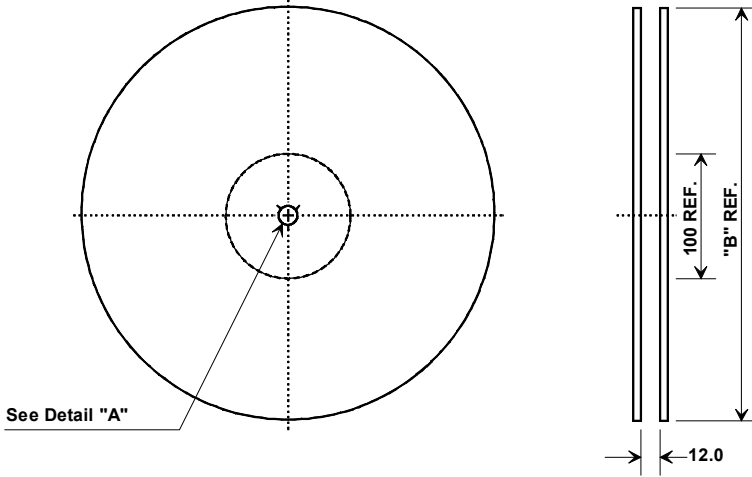


BOTTOM VIEW

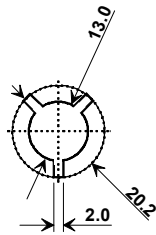


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA481

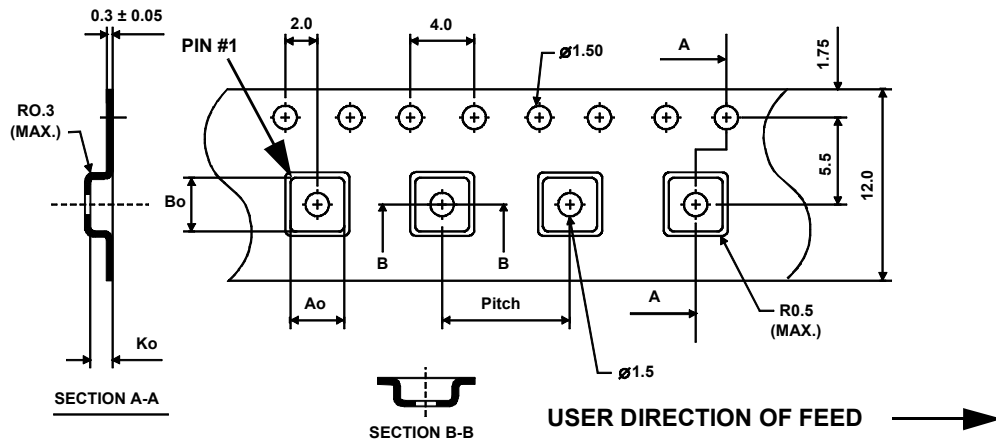


"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 ±0.1 mm
Bo	3.35 ±0.1 mm
Ko	1.40 ±0.1 mm
Pitch	8.0 ±0.05 mm
W	12.0 ±0.3 mm



RECOMMENDED REFLOW PROFILE

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 sec)
4. Time: 2 times.

